



**PATENT APPLICATION**

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. Nguyen

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of one month, extending the time for responding to the Office Action of February 7, 2006, to June 7, 2006.

The USPTO is directed and authorized to charge the statutory Petition fee of \$120.00 to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: June 5, 2006